

MULTI-LAYERED PRINTED WIRING BOARDABSTRACT OF THE DISCLOSURE

There is provided a multi-layered printed wiring board including a power supply layer (7), a ground layer (6), a signal layer (5), and insulators (8, 9) sandwiched between those layers (5, 6, 7), characterized by that the power supply layer (7) is provided with a circuit (11, 12, 13) in the form of wirings for imparting impedance thereto. The impedance imparting circuit may be composed of winding (11), intersecting (12) or spiral (13) line patterns. The invention makes it possible to provide a relatively great inductance to thereby decrease high frequency power supply current which is generated on IC/LSI operation and is to flow into decoupling capacitors. It is possible to identify a route through which a current runs into the power supply layer to thereby provide an optimal decoupling capacitor to every IC/LSI as a source of high frequency power supply current.

(Figure 3)